

■ MB7117E/H, MB7118E/H

Schottky TTL 2048-Bit
Bipolar Programmable
Read-Only Memory

Description

The Fujitsu MB7117 and MB7118 are high speed Schottky TTL electrically field programmable read only memories organized as 256 words by 8-bits. With uncommitted collector outputs provided on the MB7117 and three-state outputs on the MB7118 memory expansion is simple.

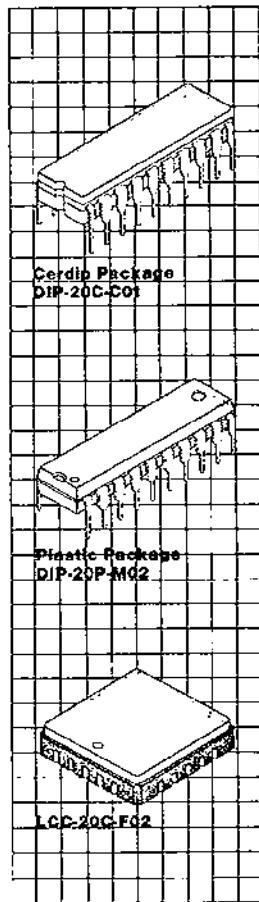
The memory is fabricated with all logic "zeros" (positive logic). Logic level "ones" can be programmed by the highly reliable DEAP™ (Diffused Eutectic Aluminum Process) according to simple programming procedures.

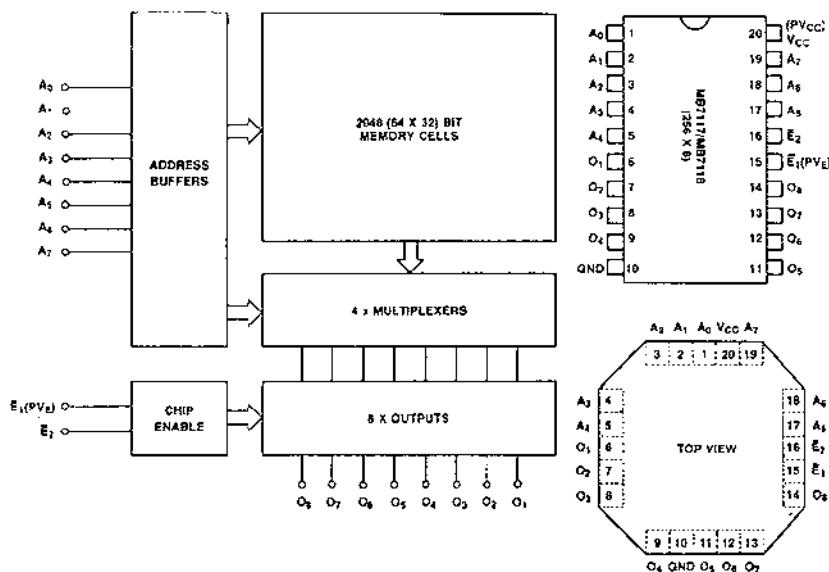
The sophisticated passive isolation termed IOP (Isolation by Oxide and Polysilicon) with thin epitaxial layer and Schottky TTL process permits minimal chip size and fast access time.

Extra test cells and unique testing methods provide enhanced correlation between programmed and unprogrammed circuits in order to perform AC, DC and programming test prior to shipment. This results in extremely high programmability.

Features

- Single +5V supply voltage
- Organized as 256 words by 8-bits, fully decoded
- Proven higher programmability and reliability
- Programming by DEAP™ (Diffused Eutectic Aluminum Process)
- Simplified, low power programming
- Low current PNP inputs
- AC characteristics guaranteed over full operating voltage and temperature range via unique testing techniques
- Fast access time, 25 nsec typ.
E—45 nsec max.
H—35 nsec max.
- TTL compatible inputs and outputs
- Open collector outputs, MB7117
- Three-state outputs, MB7118
- Two chip enables for simplified memory expansion
- Standard 20-pin DIP package
- JEDEC approved pin out

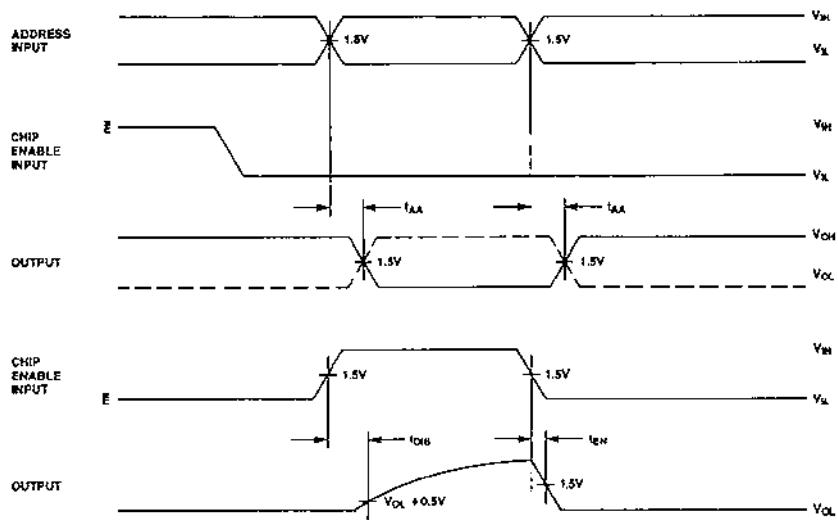


MB7117E/H, MB7118E/H
Block Diagram and Pin Assignment

Absolute Maximum Ratings
(See Note)

Rating	Symbol	Value	Unit
Power supply voltage	V _{CC}	-0.5 to +7.0	V
Power supply voltage (during programming)	V _{CC}	-0.5 to +7.5	V
Input voltage	V _{IN}	-1.5 to +5.5	V
Input voltage (during programming)	V _{PRG}	22.5	V
Output voltage (during programming)	V _{PRG}	0.5 to +22.5	V
Input current	I _{IN}	-20	mA
Input current (during programming)	I _{PRG}	+270	mA
Output current	I _{OUT}	+100	mA
Output current (during Programming)	I _{PRG}	+150	mA
Storage temperature	T _{STG}	-65 to +150	°C
Ceramic			
Plastic		-40 to +125	
Output voltage	V _{OUT}	-0.5 to V _{CC}	V

Note: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to conditions as detailed in the operational sections of this data sheet. This device contains circuitry to protect the inputs against damage due to high static voltage or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

Operation Timing Diagram

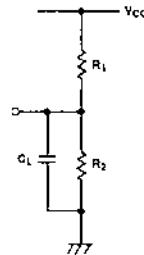


NOTE: OUTPUT DISABLE TIME IS THE TIME TAKEN FOR THE OUTPUT TO REACH A HIGH RESISTANCE STATE WHEN THE CHIP ENABLE IS TAKEN HIGH (DISABLED).
 OUTPUT ENABLE TIME IS THE TIME TAKEN FOR THE OUTPUT TO BECOME ACTIVE WHEN ALL OF CHIP ENABLES ARE TAKEN LOW (ENABLED). THE HIGH RESISTANCE STATE IS DEFINED AS A POINT ON THE OUTPUT WAVEFORM EQUAL TO A 1V OF 0.5V FROM THE ACTIVE OUTPUT LEVEL.

AC Test Conditions

Input Conditions
 Amplitude: 0V to 3V
 Rise and Fall Time: 5 ns from 1V to 2V
 Frequency: 1MHz

	R ₁	R ₂	C _L
t _{AA}	300Ω	800Ω	30pF
t _{DS}	360Ω	800Ω	30pF
t _{EN}	300Ω	800Ω	30pF



Input/Output Circuit Information

Input Circuit

Schottky TTL circuit technology is used in the input circuit to achieve high-speed operation. A PNP transistor in the first stage of the input circuit improves input high/low current characteristics remarkably. The input circuit also includes a protection diode for reliable operation.

Open Collector Output

The open collector output is often utilized in high-speed applications where power dissipation must be minimized. When the device is switched, there is no current sourced from the supply rail. Consequently, the current spike normally associated with TTL totem-pole outputs is eliminated. In high-frequency applications, this minimizes noise problems (false triggering) as well as power drain. For example, the transient current (low impedance high-level to low impedance low-level) is typically 30mA for the MB7118 (three-state) compared to 0mA for the MB7117 (open-collector).

Three-State Output

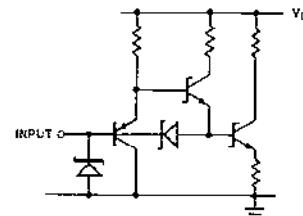
A "three-state" output is a logic element which has three distinct output states of ZERO, ONE and OFF (wherein OFF represents a high-impedance condition which can neither sink nor source current at a definable logic level). Effectively, then, the device has all the desirable features of a totem-pole TTL output (e.g., greater noise immunity, good rise time, line driving capacity), plus the ability to connect to bus-organized systems.

In the case where two devices are on at the same time, the possibility exists that they may be in opposite (one a ONE and one a ZERO) impedance states simultaneously; thus, the short circuit current from one enabled device may flow through the other enabled device. While physical damage under these conditions is unlikely, system noise problems could result. Therefore, the system designer should consider these factors to ensure that this condition does not exist.

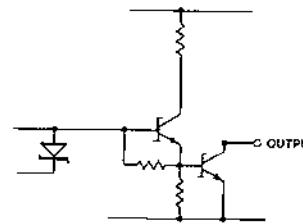
Also in the output circuit, Schottky TTL circuit technology is used to achieve high-speed operation. A PNP transistor is

also provided in the output circuit and is effective in decreasing a load for the Chip Enable circuit.

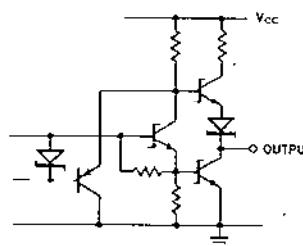
MB7117/MB7118 Input Circuit



MB7117 Output Circuit

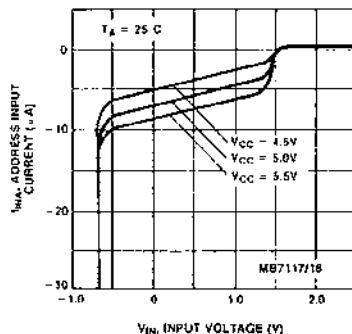


MB7118 Output Circuit

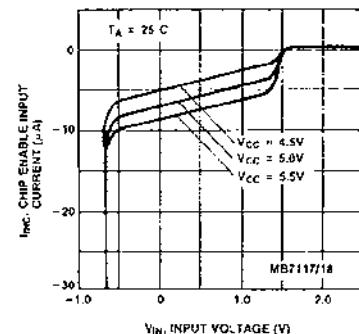


**Typical Characteristics
Curves**

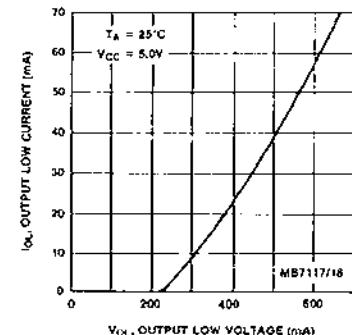
**I_{INA} Input Current
vs. V_{IN} Input Voltage**



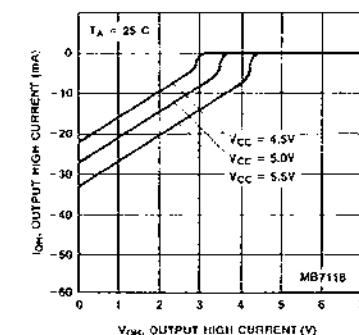
**I_{INC} Input Current
vs. V_{IN} Input Voltage**



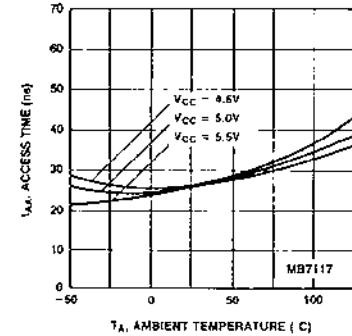
**I_{OL} Output Low Current
vs. V_{OL} Output Low Voltage**



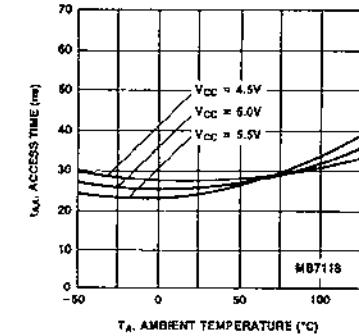
**I_{OH} Output High Current
vs. V_{OH} Output High Voltage**



**t_{AA} Access Time
vs. Ambient Temperature**

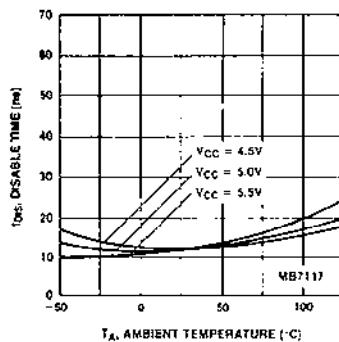


**t_{AA} Access Time
vs. Ambient Temperature**

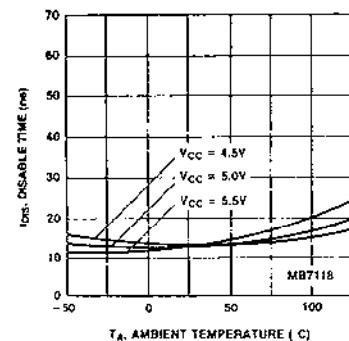


Typical Characteristics
Curves
 (Continued)

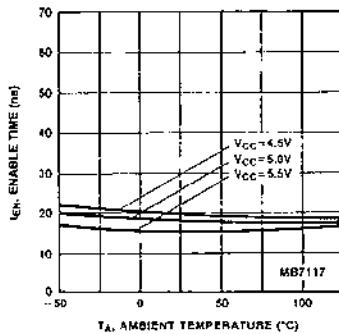
**t_{DIS} Disable Time
 vs. Ambient Temperature**



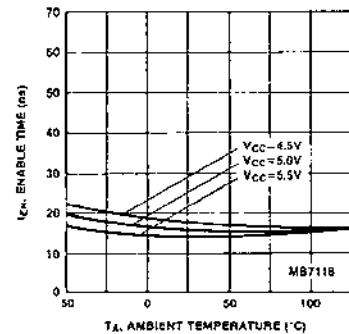
**t_{DIS} Disable Time
 vs. Ambient Temperature**



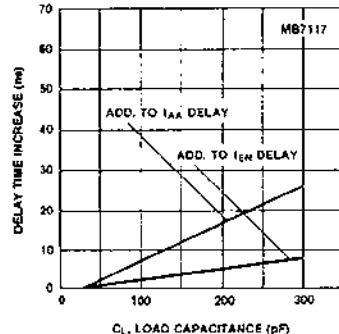
**t_{EN} Enable Time
 vs. Ambient Temperature**



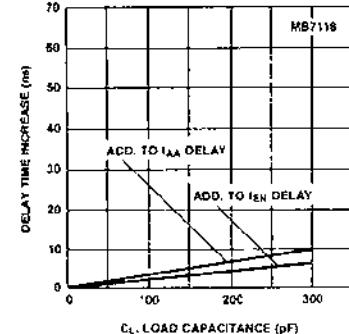
**t_{EN} Enable Time
 vs. Ambient Temperature**



**Delay Time Increase
 vs. C_L Load Capacitance**

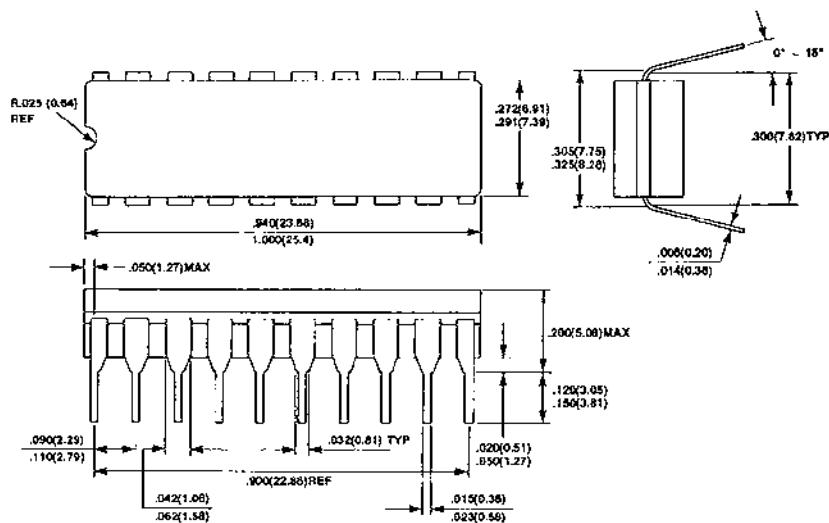


**Delay Time Increase
 vs. C_L Load Capacitance**

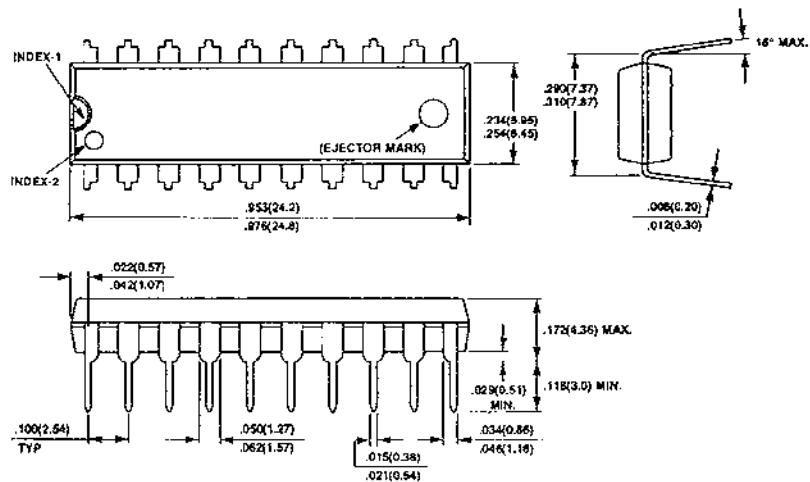


Package Dimensions
Dimensions in inches
(millimeters)

20-Pin Cerdip Dual In-Line Package
DIP-20C-C01



20-Pin Plastic Dual In-Line Package
DIP-20P-M02



Package Dimensions
(Continued)
Dimensions in Inches
(millimeters)

20-Pad Ceramic (Frit Seal) Leadless Chip Carrier
(Case No.: LCC-20C-FO2)

